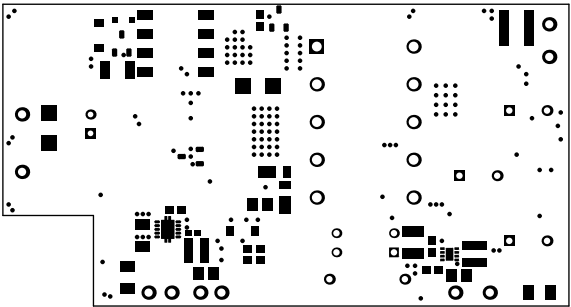
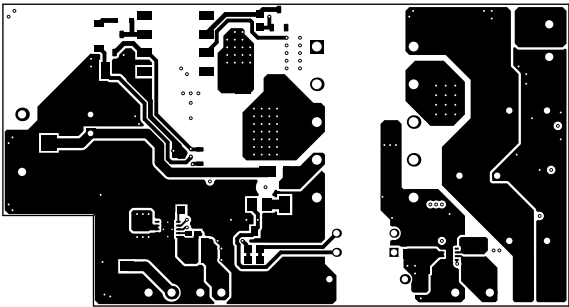


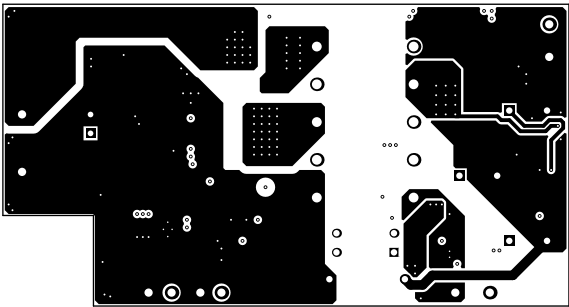
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20396	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 11/20/2017 3:18:05 PM	TEXAS INSTRUMENTS	



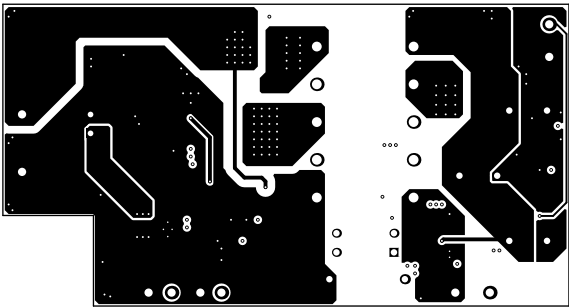
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20396	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 11/20/2017 3:18:07 PM	TEXAS INSTRUMENTS	



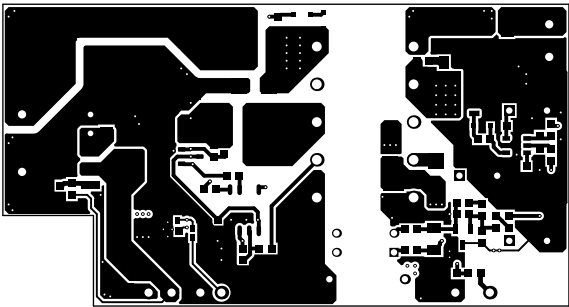
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20396	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 11/20/2017 3:18:08 PM	TEXAS INSTRUMENTS	



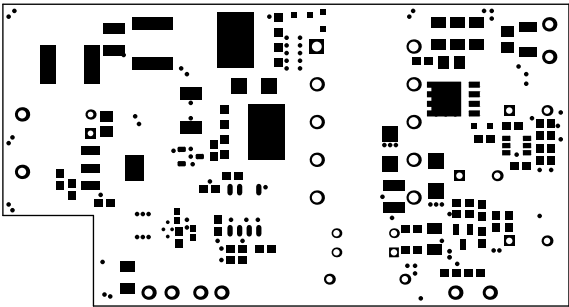
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20396	REV: B	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 11/20/2017 3:18:10 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20396	REV: B	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 11/20/2017 3:18:11 PM	TEXAS INSTRUMENTS	

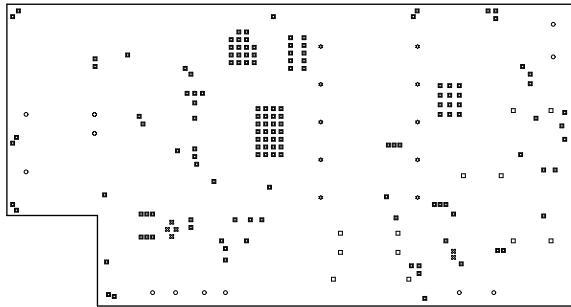


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20396	REV: B	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 11/20/2017 3:18:13 PM	TEXAS INSTRUMENTS	

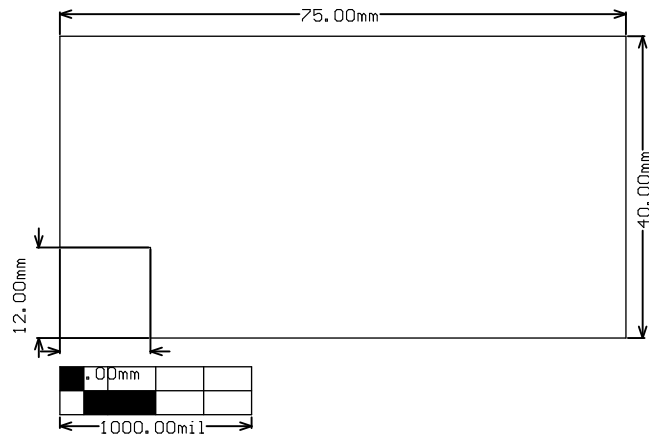


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20396	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/20/2017 3:18:14 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
☒	6	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
■	144	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	2	28.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	
□	12	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
○	10	43.00mil (1.092mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	10	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
	184 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20396	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 11/20/2017 3:18:16 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20396	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 11/20/2017 3:18:18 PM	TEXAS INSTRUMENTS	

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